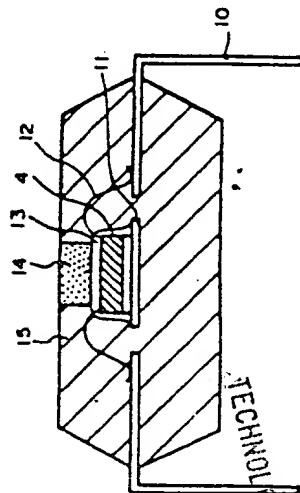


(54) SEMICONDUCTOR DEVICE

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**PURPOSE:** To obtain a package having an incident light part at lower cost by a method wherein a semiconductor chip with the light-receiving face thereof facing upward is fixed to the island part of a lead frame, a light transmitting plate is equipped thereon through a light transmitting adhesive agent and the whole is surrounded with a molded package, excluding lead parts to be led out to the outside.

**CONSTITUTION:** An EPROM chip 4 is fixed to the central island part 11 of a lead frame having leads 10 bending at the outside and this terminal is connected with lead frames mutually facing the terminal using gold wires 12. Then, on the chip 4 is adhered a light transmitting plate 14, which is capable of transmitting about 2,000~3,000 Å of ultraviolet rays, such as a high-purity alumina plate, etc., by using a bonding agent 13 such as silicon-system varnish, etc. After then, the part except the leads 10 protruding outside, is surrounded with a molded package 15 consisting of an epoxy resin, etc. According to such a method, the cost for manufacturing a package can be significantly cut down without using a ceramic package with window, etc.



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